Single Axis Resonant Integrated MEMS Mirrors Datasheet

A9R Series: A9R8.1-800DAL, A9R12.1-1200DAL, A9R14.1-1400DAL

OVERVIEW

Mirrorcle Technologies **Single-Axis Resonant MEMS Mirrors** are based on proprietary fabrication technology. They provide fast optical beam steering, while requiring ultra-low power. The mirrors deflect laser beams or images to optical scanning angles of up to ±18°. Compared to large-scale galvanometer-based optical scanners, these devices require several orders of magnitude less driving power: continuous operation of the electro-static actuators that drive the mirror tilt rotation dissipates less than 1mW of power.

Mirrorcle Technologies MEMS Mirrors are made entirely of monolithic Single-Crystal Silicon (SCS), resulting in **excellent repeatability and reliability**. Flat, smooth mirror surfaces are coated with a thin film of metal with high broadband reflectance.

FEATURES

- ☐ **Single-axis Resonant Integrated** MEMS Mirror
- ☐ **0.8mm, 1.2mm, 1.4mm diameter** mirrors
- ☐ Flat, Aluminum-coated mirror
- ☐ ±8.5° Mechanical (Resonant Only) Rotation
- ☐ Electro-static Actuation
- ☐ Ultra-low power consumption
- ☐ High robustness and reliability
- ☐ Wide operating temperature range
- ☐ Window options for visible and IR wavelengths

Applications

- ☐ Lidar / 3D Sensing
- ☐ Pico-Projection
- ☐ Biomedical Microscopy and Imaging
- ☐ Free-space optical communication (FSOC)
- ☐ Metrology
- ☐ Laser Marking

MODULAR DESIGN

Mirrorcle actuators lend themselves inherently to a modular design approach. Each actuator can utilize electrostatic rotators of arbitrary length, arbitrarily stiff linkages, and arbitrarily positioned mechanical rotation transformers. In addition, the device can have an arbitrarily large mirror diameter. This modularity easily allows the devices to be customized for any application requirement. With over 20 major design series and manufacturing generations, multiple sub-generations of design tuning for a specific customer or set of specifications, the complete list of working designs has over 100 device types. Several of the designs are in series production.

Due to this design flexibility and a wide variety of beam steering applications with widely different specifications, we provide many types of gimbal-less two-axis actuator designs. Single-axis devices are in some cases based on dual-axis devices with only the X-axis activated in assembly. However **single-axis resonant** devices are a specialized category with very stiff small actuators, specifically optimized for stable and pure 1D sinusoidal scans.

PRELIMINARY

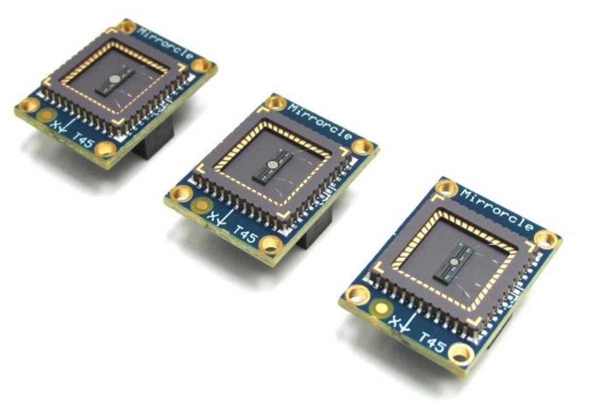


Figure 1. Image of the three devices, A9R8.1-800DAL-TINY48.4, A9R12.1-1200DAL-TINY48.4, A9R14.1-1400DAL-TINY48.4. The connectorized package "TINY48.4" is 15mm x 20mm x 9mm

RESONANT SCANNING MODE

Typical Mirrorcle (quasi-static) devices can operate from DC response to dynamic, resonant modes. However, resonant devices operate only near or at the resonant frequency. Their actuators utilize very stiff single-crystal silicon springs to support the MEMS mirror and to provide restoring force during actuation. In **resonant mode,** users drive the actuators near the narrow, high gain resonance to obtain fast scans with large angles of deflection. Motion is limited to very narrowband, "pure" and stable sinusoidal trajectories with a phase lag to the applied voltage.

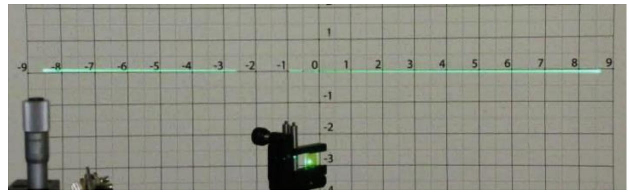


Figure 2. resonant scanning mode on the x-axis (sinusoidal beam motion) used to achieve a large, fast, single-aixs resonant axis scan.

MEMS Mirror Device Specifications

ABSOLUTE MAXIMUM RATINGS

The absolute maximum ratings are defined as limits to the electrical and mechanical design of the MEMS mirror, where exceeding the maximum voltage or the maximum mechanical tilt can cause permanent physical damage to the device. The maximum voltage is defined as the voltage between any two terminals on the device. E.g. X+ to ground, or X+ to X-.
Mirror flatness can be affected by exceeding the maximum temperature rating. Higher temperatures can change the stresses of the mirror's reflectivity coating and can permanently change the radius of curvature. The mirror surface temperature can also be increased by high laser powers, not just the temperature of the environment.

Parameter	Test Conditions	Max.	Units
Absolute Maximum Mechanical Tilt	Both axes simultaneously, each axis tilted with stated angle	12.5	Deg
Absolute Maximum Voltage	Voltage between any two terminals	155	V
Absolute Maximum Temperature	Max temperature can affect mirror surface quality	125	°C

RECOMMENDED OPERATING CONDITIONS

Although the mirror can be actuated by waveforms with components from DC to practically infinity, with varied corresponding responses, for convenience of listing recommended conditions, we distinguish two regimes of operation: 1) static or quasistatic and 2) dynamic or resonant. The DC Static Mechanical tilt is defined as the deflection range of the MEMS mirror with DC (or equivalent very slow actuation). In the case of resonant devices, this is very limited (typically ±0.1°). The Dynamic Mechanical Tilt is defined as peak amplitude mechanical tilt during sinusoidal motion at frequencies closer to the resonant frequency. This sinusoidal resonant response of the MEMS mirror results in large mechanical tilt. With drive signals near resonance, or containing signal components near resonance, users should test with low drive voltages and ramp up to ensure the device is never scanning beyond the Maximum recommended tilt angles to prevent any damage to the device. The device **response in angle can be arbitrarily adjusted by scaling the Vdifference** of the sinusoid signal being used to drive the resonant device.

PRELIMINARY

Parameter	Test Conditions	Min.	Typ.	Max.	Units
DC Static Mechanical Tilt	Vbias = 90V, VdifferenceMax = 120V		±0.1		Deg
Dynamic Mechanical Tilt	Vbias = 90V, Sinusoidal, near first resonance		±8.5	±9.0	Deg
VdifferenceMax	Vbias = 90V		80	120	V
First Resonant Frequency (X-Axis)	A9R8.1-800DAL	20525		23850	Hz
	A9R12.1-1200DAL	11850		13850	Hz
	A9R14.1-1400DAL	7775		9050	Hz
First Resonance Quality Factor	X-Axis	50		200	
Recommended Low Pass Filter (LPF)	X-Axis	50000			Hz
X-Axis Step Response	0° to 2° Step Input with Recommended LPF		N/A		ms
Point-to-Point Precision	Dynamic, repeatability of angle after an oscillation period.		2.5	5.0	mDeg.

WARNING

Proper ESD protection and a clean environment is needed when handling Mirrorcle MEMS mirrors to prevent any damage from electro-static discharge, or any dust particles landing on the MEMS mirror.

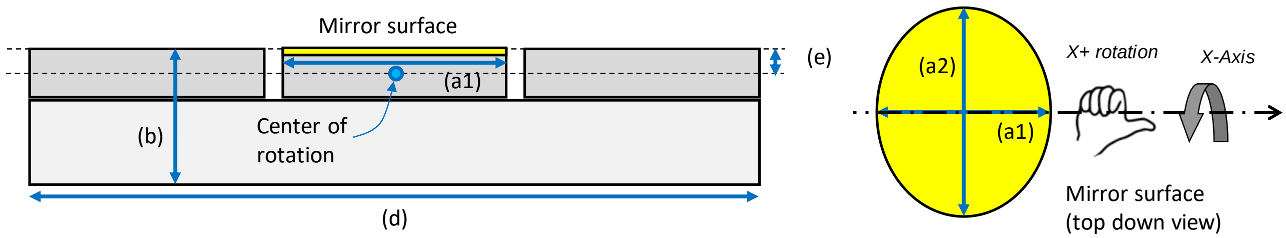
PRELIMINARY

MIRROR SPECIFICATIONS

Mirrorcle Technologies MEMS Mirrors are fabricated out of single-crystal Silicon wafers of the same prime grade and quality that is used for the manufacturing of integrated circuits such as PC microprocessors. Because similar mass production processes are utilized to obtain highest manufacturing repeatability, quality, and lowest cost, Silicon is used as the base material. The wafer surfaces and therefore fabricated mirror surfaces are polished to below 1nm roughness with world's best polishing technologies. Also unique to Silicon based microfabrication is the availability of methodologies to make the surfaces ultra-clean prior to mirror metallization. Furthermore, the Silicon material is inherently without any residual stress from its manufacturing and maintains this property after mirror microfabrication. Therefore, Silicon mirrors have extremely high flatness, with curvature often below level measurable with conventional interferometers. As the base material in a MEMS mirror, Silicon has the optimal properties of smoothness, cleanliness, and flatness.

In the final manufacturing step for optical beam steering applications, the Silicon mirror must be coated for high reflectance at required optical wavelengths. In our standard production processes, we coat the Silicon mirrors with a thin layer of Aluminum. All in-stock MEMS mirrors are available with the Aluminum coating. Some of the designs in R&D production processes are coated with Gold.

Device mechanical dimensions are listed below. The Mirror surface diameter is defined by (a). The total die thickness is defined as (b), with the device layer being (c). The total die width is defined as (d). The distance from the center of rotation of the device is off to the top of the mirror surface is offset, defined by (e).



Parameter	Test Conditions	Min.	Typ.	Max.	Units
Mirror Diameter (a1)	A9R8.1-800DAL	0.76	0.80	0.84	mm
	A9R12.1-1200DAL	1.07	1.11	1.15	mm
	A9R14.1-1400DAL	1.25	1.29	1.33	mm
Mirror Diameter (a2)	A9R8.1-800DAL	0.81	0.85	0.89	mm
	A9R12.1-1200DAL	1.16	1.20	1.24	mm
	A9R14.1-1400DAL	1.36	1.40	1.44	mm
Mirror Radius of Curvature	Spherical term fit over whole mirror	5			m
Mirror Surface Roughness	RMS value (Rq)	10			nm
Mirror Coating	Metal thin-film (no protection layer)	Aluminum			
Mirror Reflectivity	400nm-2000nm, 22.5° AOI	80			%
Mirror Coating Thickness	Metallization layer	55	70	85	nm
Total Die Thickness (b)		0.4852	0.4912	0.4972	mm
Total Die Width (d)	Rectangular Die (Min x Max) ±0.05mm	1.733		5.2	mm
Mirror center of rotation (e)	Difference between center of rotation (origin) to top of mirror surface	0.015	0.02	0.025	mm

ENVIRONMENTAL AND MECHANICAL CONDITIONS

Parameter	Test Conditions	Min.	Typ.	Max.	Units
Operating Temperature Range	No Condensation, Relative Humidity < 60%	-40		105	°C
Storage Temperature Range	No Condensation, Relative Humidity < 60%	-40		105	°C
Mechanical Shock	Survives at least stated level (all 3 axes)	500			g
Vibration	Passes tests (20g, 4 min/cycle, 4 cycles/ axis)	20		2000	Hz

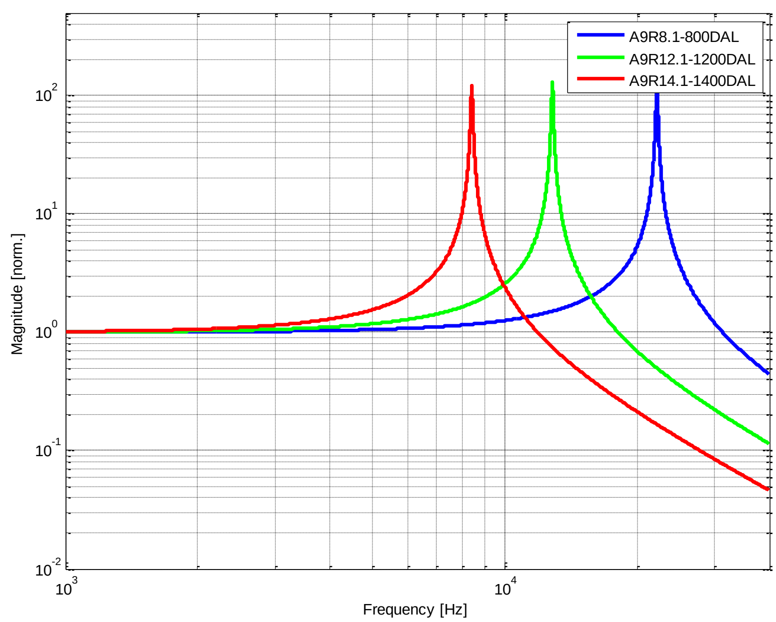
PRELIMINARY

MEMS Mirror Device Typical Characteristics

Note: These curves shown below are typical responses that are characteristic for this type of device. Individual device responses may vary by ±15%

Small Signal Frequency Response - Magnitude

A wide band (0-60kHz) and very small amplitude noise waveform is applied to the MEMS driver and the mirror's response is measured by the 2D PSD for X axis. From the input (waveform) and output (device angle), a complex frequency response (amplitude and phase) is obtained and plotted for the X axis.



Refer to Mirrorcle Application Note AN005 for Resonant Driving Methodologies:

https://www.mirrorcletech.com/pdf/AN/AN005 - MEMS Mirror Resonant Scanning.pdf

MEMS Mirror Driving Recommendations

LINEARIZED DRIVING OF FOUR-QUADRANT (4Q) DEVICES

Mirrorcle Development Kits and OEM MEMS drivers utilize a device-specific method of driving the 4Q MEMS actuators with a Bias-Differential Quad-channel (BDQ) scheme. This scheme linearizes actuators' voltage-angle relationship and improves smooth transitions from one actuator to another within the device. In this mode both the positive rotation portion and the negative rotation portion of each rotator are always (differentially) engaged, and therefore the voltages and torques are always continuous. All Mirrorcle MEMS drivers are designed to operate in this mode and therefore have four channels with biased output (two differential pairs). Inputs are either digital or analog and only two channels are required to command x-axis and y-axis position.

MEMS MIRROR MODULE

MEMS Mirror Modules (MMM) combine a MEMS Mirror with a MEMS Driver, allowing users to conveniently and safely control MEMS mirrors from their own hardware platforms (e.g. NIDAQ, MCU or FPGA module).

The recommended MEMS Mirror Module for this product includes the Analog-Input MEMS Driver with T180 driving, also termed "BDQ PicoAmp T180" (P/N DR-11-055-00). As mentioned, use of the Analog MEMS Driver requires bench-top lab equipment such as function generators or a data acquisition (DAQ) card. Its -10V to +10V input range is particularly well suited for use with National Instruments NIDAQ cards.

For convenient experimentation with the driver, a breakout PCBA is added in the bundle which breaks out the MEMS Driver input connector into convenient terminals and test points.

DRIVING RECOMMENDATIONS

Mirrorcle strongly recommends all first-time users of the MEMS mirrors to start with a Development Kit. The Development Kit comes with a USB MEMS Controller, three different MEMS mirrors, red laser and optical breadboarding with mounts for the MEMS mirror and laser. The Development Kit also includes an extensive Software Suite with SDKs in C++, Matlab and LabView, with options to upgrade to Python, and C++ for Linux (Ubuntu x64 platform). In addition to the SDKs, the Software Suite also includes Windows based Applications like MirrorcleDraw, MTIDevice-Demo, Mirrorcle Linear Raster, etc. The development kit allows users to quickly setup the MEMS mirror to perform an incoming inspection and evaluate the device for their specific application. MirrorcleDraw is a powerful software that enables the user to generate or import content, quickly change the size, rotation, filter settings, refresh rate and many other settings.

For users ready to integrate the MEMS Mirror into their applications, various levels of integration are available, starting at the lowest level with analog input or digital input MEMS Drivers (see MEMS Mirror Module section earlier). MEMS Drivers require the user to generate the MEMS Mirror position signals on their own processor / platform.

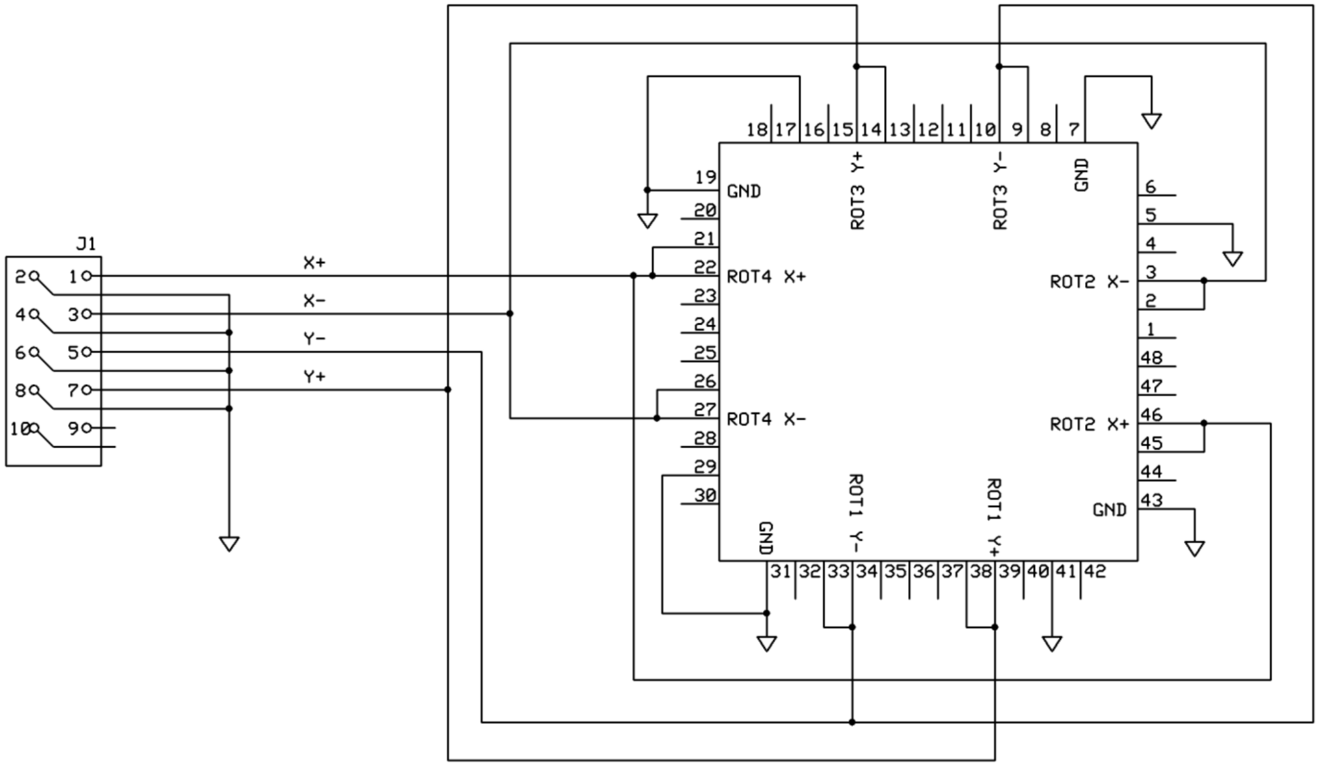
For users that prefer a higher level of integration, and use of software to interface with the MEMS Mirror, a MEMS Mirror System (MMS) is recommended. An MMS includes a MEMS Mirror with a USB MEMS Controller and Software. The USB MEMS Controller is able to receive all the same API commands in the various software languages provided in the SDKs. However, in production it is offered in multiple different OEM versions with different form factor and features.

Recommended MEMS Mirror Module Part Number:

- ☐ EMMM502-C/W/EP: MEMS Mirror Module, 1D Resonant, 0.8mm AL, C, AINR-ED
- ☐ EMMM502-AB/W/EP: MEMS Mirror Module, 1D Resonant, 0.8mm AL, AB, AINR-ED
- ☐ EMMM512-C/W/EP: MEMS Mirror Module, 1D Resonant, 1.2mm AL, C, AINR-ED
- ☐ EMMM512-AB/W/EP: MEMS Mirror Module, 1D Resonant, 1.2mm AL, AB, AINR-ED

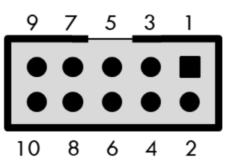
PRELIMINARY

TINYPCB CIRCUIT AND CONNECTIONS



PRELIMINARY

10 - Pin Header – J1		
Pin	**Name**	**Description**
1	HV_A (X+)	MEMS Channel X+
2	GND	Ground
3	HV_B (X-)	MEMS Channel X-
4	GND	Ground
5	HV_C (Y-)	MEMS Channel Y-
6	GND	Ground
7	HV_D (Y+)	MEMS Channel Y+
8	GND	Ground
9	N/C	No Connection
10	N/C	No Connection



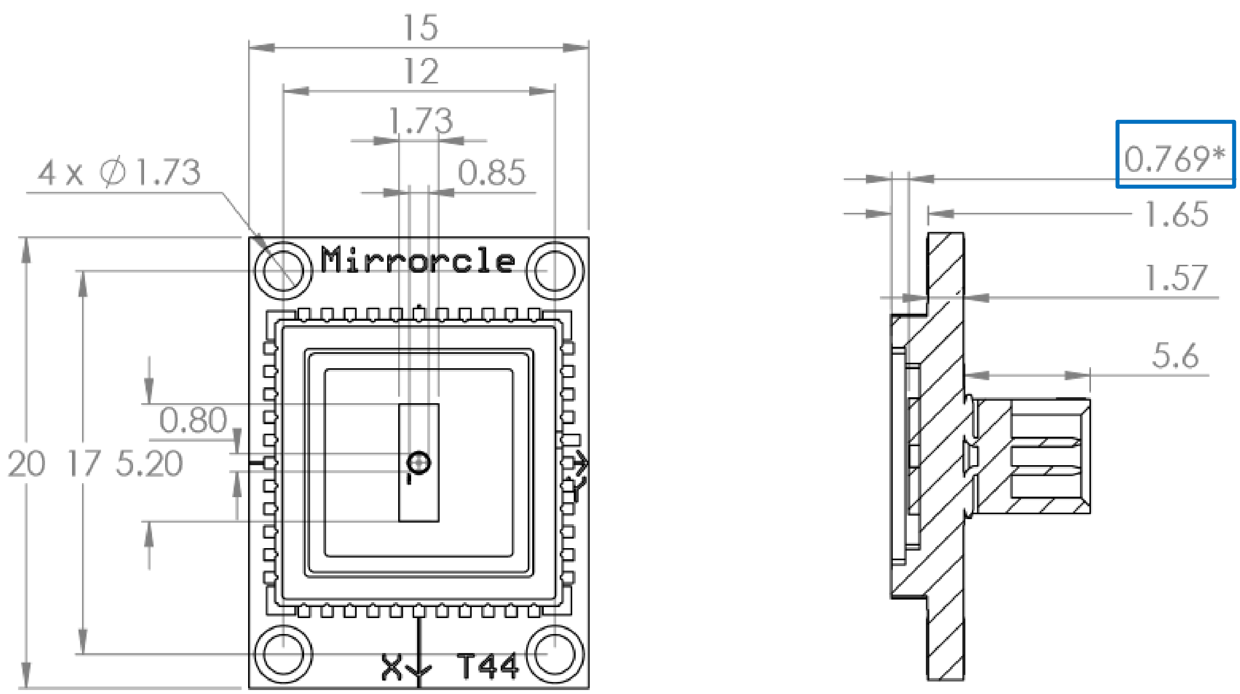
View from back

Connector Part No.	Pins	Mating Cables and Sockets
Digikey P/N: 1175-1629-ND	10	Digikey P/N: SAM8219-ND

HIGH VOLTAGE WARNING

Mirrorcle MEMS Drivers are High Voltage Amplifiers that can produce hazardous voltages and currents which may be harmful. Use caution and exercise preventative safety measures to prevent contact between the high voltages and any personnel or equipment.

A9R8.1-800DAL-TINY48.4 DIMENSIONS



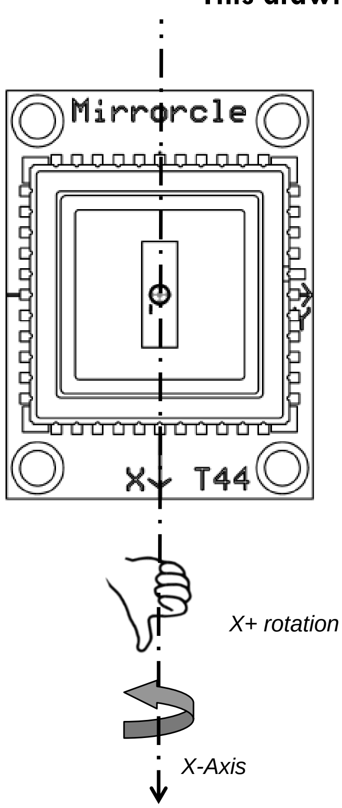
*Distance from surface of MEMS mirror to top of LCC Cavity

This drawing is of the device and package only. See next page for cover attach.

MEMS Mirror and LCC Cavity Tolerances: ±100µm

PCB Parts, Holes and Dimensions Tolerances: ±125µm

All units in mm



Definitions:

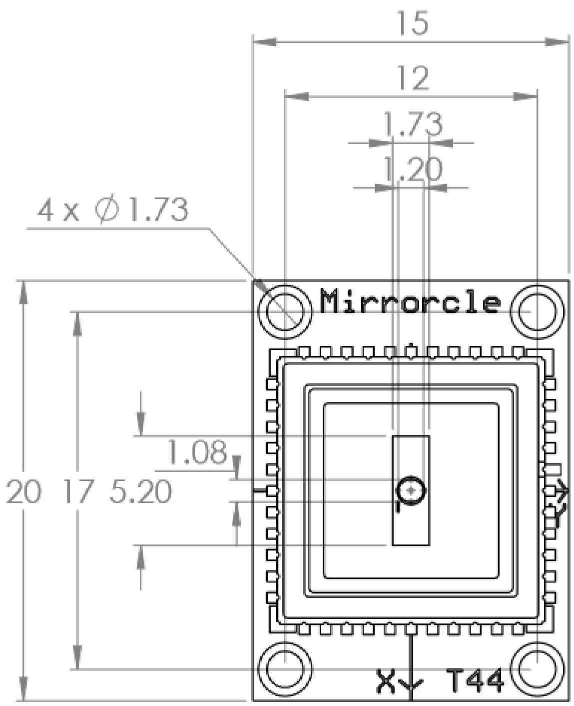
Vdifference(X) = HV_A – HV_B

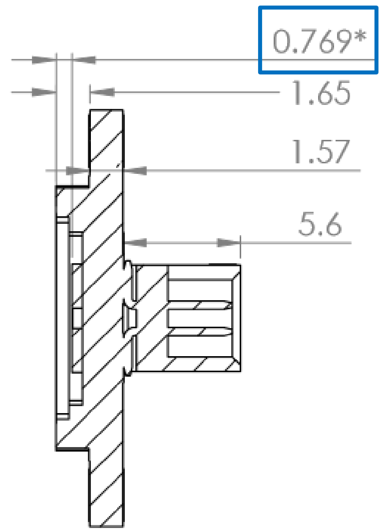
X Axis:

Vdifference(X) >0 results in X+ rotation about the x-axis

Vdifference(X) <0 results in X- rotation about the x-axis

A9R12.1-1200DAL-TINY48.4 DIMENSIONS





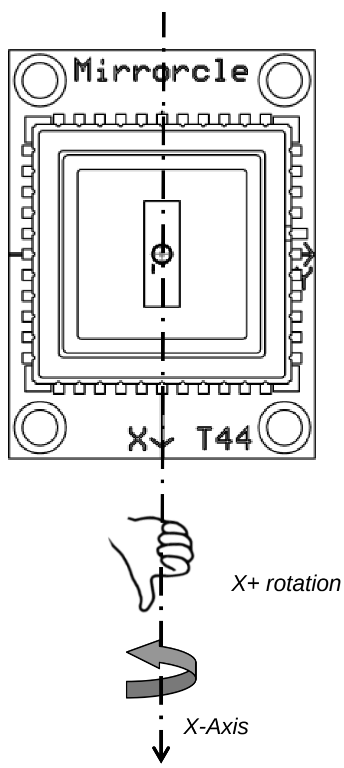
*Distance from surface of MEMS mirror to top of LCC Cavity

This drawing is of the device and package only. See next page for cover attach.

MEMS Mirror and LCC Cavity Tolerances: ±100µm

PCB Parts, Holes and Dimensions Tolerances: ±125µm

All units in mm



Definitions:

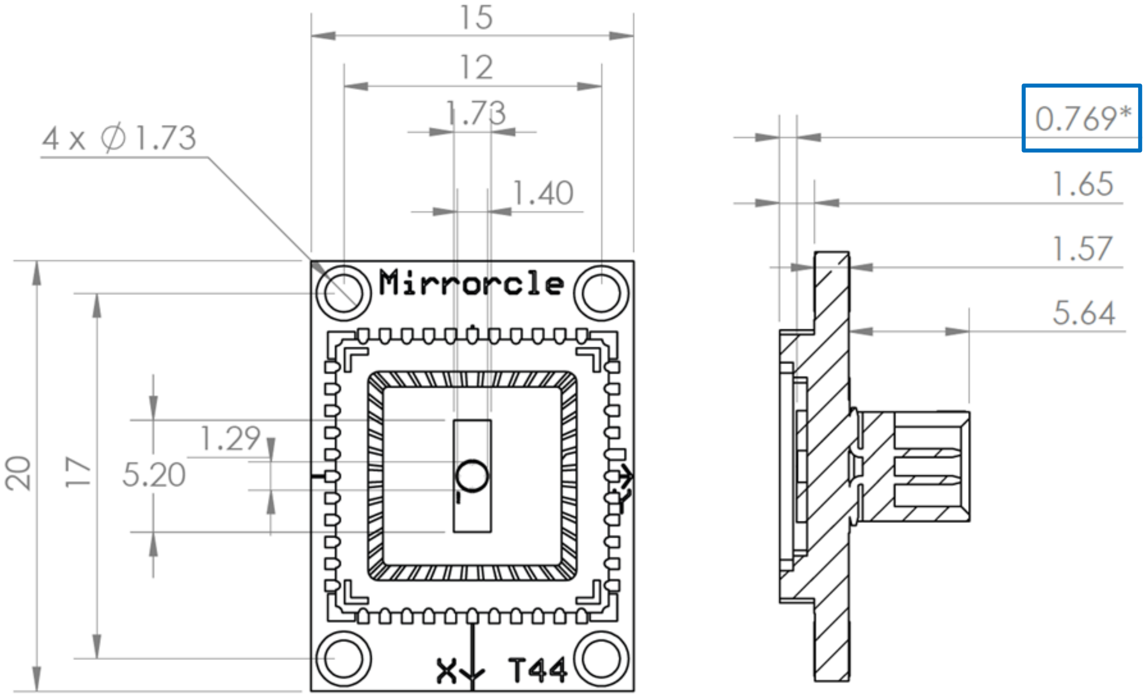
Vdifference(X) = HV_A – HV_B

X Axis:

Vdifference(X) >0 results in X+ rotation about the x-axis

Vdifference(X) <0 results in X- rotation about the x-axis

A9R14.1-1400DAL-TINY48.4 DIMENSIONS



*Distance from surface of MEMS mirror to top of LCC Cavity

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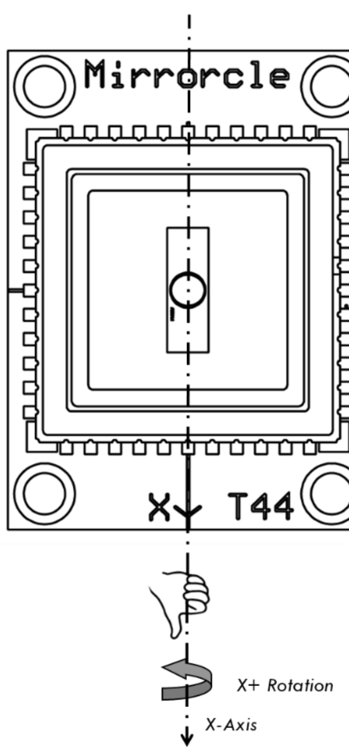
MEMS Mirror and LCC Cavity Tolerances: ±100µm

PCB Parts, Holes and Dimensions Tolerances: ±125µm

All units in mm



Definitions:

Vdifference(X) = HV_A – HV_B

X Axis:

Vdifference(X) >0 results in X+ rotation about the x-axis

Vdifference(X) <0 results in X- rotation about the x-axis

MEMS Mirror Part Name and Cover Attach Specifications

MEMS Mirror Part Name Format:

AAAA.A-BBBBCC-DDDD-EE/FF/GG

- AAAA.A: MEMS actuator Design ID (e.g.: A9R12.1)
- BBBB: Mirror diameter in microns (e.g.: 1200), D designation is used for elliptical mirrors
- CC: Mirror coating (AL, AU, or SI for uncoated Silicon)
- DDDD: MEMS carrier package ID (e.g.: TINY48.4)
- EE: Cover window selection (e.g.: B)
- FF: Wedge option: 'W' for Wedge, 'F' for Flat
- GG: Cover attachment method (e.g.: EP)

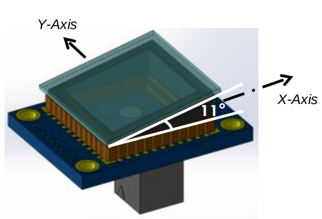
Window Coating Options

Window Coating	Coating Range [Min]	Coating Range [Max]	AOI [°]	Transmittance [%]	P/N Section E
Type A	400 nm	675 nm	22.5°	>98%	**A**
Type B	675 nm	1040 nm	22.5°	>98%	**B**
Type C	1040 nm	1600 nm	22.5°	>98%	**C**
Type AB	400 nm	980 nm	22.5°	>96%	**AB**
No coating	400 nm	2000 nm	22.5°	>88%	**NC**

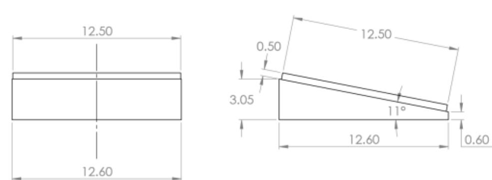
- All four window types transmittance are specified for ±10° from AOI (Angle of Incidence) of 22.5°

Window Mounting – Wedged or Flat (FF section in Part Name above)

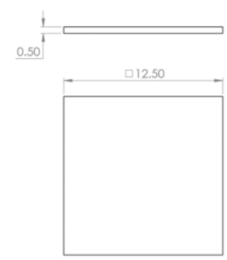
- The AR-coated window can be mounted flat on the package, or on an anodized aluminum wedge with a tilt to avoid reflections from the window appearing within the MEMS field-of-regard.
- The standard wedge is designed with a 11° tilt about the MEMS Y-axis (negative rotation about the Y-axis, sending the residual reflection UP)



Axes Orientation: Window with Wedge



Mechanical Dimensions: Window with Wedge



Mechanical Dimensions: Flat Window

Package Cover Attachment Options (GG section above)

- There are 4 methods of attaching the cover to the package:
- The cover is permanently attached to the package using adhesive. Part: /**EP**
- The cover is attached to the MEMS package using double-sided tape on all 4 edges. Part: /**TP**
- The cover is attached (lightly) to the MEMS package using double-sided tape on 2 edges. Part: /**2TP**
- A cover with temporary window (uncoated) is lightly attached for easy removal using double-sided tape on only 2 edges. Part: /**TW**

Example with Wedge and A-Type Window with Epoxy: A9R12.1-1200DAL-TINY48.4-A/W/EP

Example without Wedge and B-Type Window with Tape: A9R12.1-1200DAL-TINY48.4-B/F/TP

DISCLAIMERS AND WARRANTY STATEMENT

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Mirrorcle MEMS devices are recommended to be driven by Mirrorcle driver electronics. Use with MEMS Drivers not manufactured by Mirrorcle Technologies voids warranty. Removal of window and any significant device alteration including soldering voids warranty. Qualified incoming inspection of the MEMS Mirror products, as required by Terms and Conditions of sale shall be performed with Mirrorcle Controller and Software.

Terms and Conditions of Sale: www.mirrorcletech.com/pdf/MTI-Sales-Terms.pdf

ADDITIONAL RESOURCES

Development Kits: www.mirrorcletech.com/wp/products/devkits/

Products List: https://www.mirrorcletech.com/pdf/Mirrorcle_Products_List.pdf

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